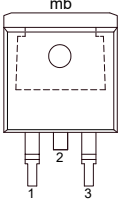



| Symbol                         | Parameter                         | Conditions  | Min | Typ | Max  | Unit             |
|--------------------------------|-----------------------------------|---|-----|-----|------|------------------|
|                                |                                   | $V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; T2- G+;<br>$T_j = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 7</a>                       | -   | 11  | 25   | mA               |
| $I_H$                          | holding current                   | $V_D = 12\text{ V}$ ; $T_j = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 9</a>   | -   | 4   | 30   | mA               |
| $V_T$                          | on-state voltage                  | $I_T = 15\text{ A}$ ; $T_j = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 10</a>  | -   | 1.4 | 1.65 | V                |
| <b>Dynamic characteristics</b> |                                   |   |     |     |      |                  |
| $dV_D/dt$                      | rate of rise of off-state voltage | $V_{DM} = 402\text{ V}$ ; $T_j = 125\text{ }^\circ\text{C}$ ; ( $V_{DM} = 67\%$ of $V_{DRM}$ ); exponential waveform; gate open circuit | -   | 50  | -    | V/ $\mu\text{s}$ |

## 5. Pinning information

Table 2. Pinning information

| Pin | Symbol | Description                    | Simplified outline  | Graphic symbol  |
|-----|--------|--------------------------------|---|---|
| 1   | T1     | main terminal 1                |  <p><b>D2PAK (SOT404)</b></p> |  <p>sym051</p> |
| 2   | T2     | main terminal 2                |   |   |
| 3   | G      | gate                           |   |   |
| mb  | T2     | mounting base; main terminal 2 |   |   |

## 6. Ordering information

Table 3. Ordering information

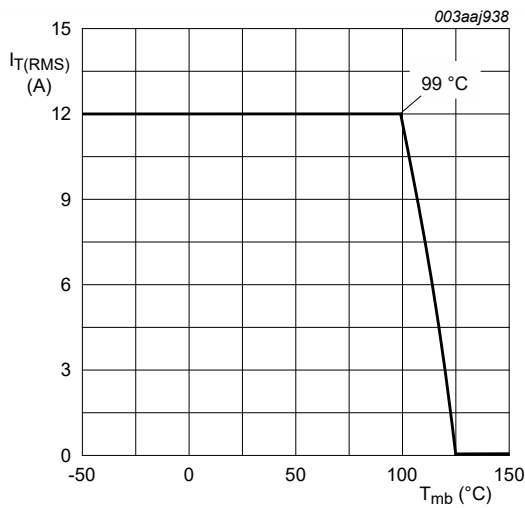
| Type number | Package |  |         |
|-------------|---------|--|---------|
|             | Name    | Description  | Version |
| BT138B-600E | D2PAK   | plastic single-ended surface-mounted package (D2PAK); 3 leads (one lead cropped) | SOT404  |

## 7. Limiting values

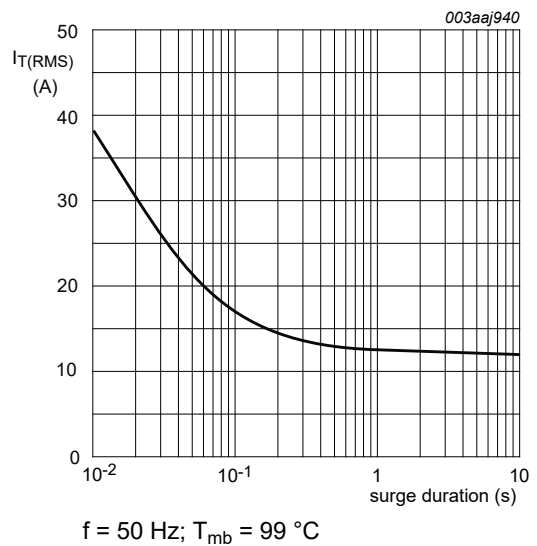
**Table 4. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol       | Parameter                            | Conditions   | Min | Max | Unit                   |
|--------------|--------------------------------------|--|-----|-----|------------------------|
| $V_{DRM}$    | repetitive peak off-state voltage    |  | -   | 600 | V                      |
| $I_{T(RMS)}$ | RMS on-state current                 | full sine wave; $T_{mb} \leq 99\text{ }^{\circ}\text{C}$ ; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>        | -   | 12  | A                      |
| $I_{TSM}$    | non-repetitive peak on-state current | full sine wave; $T_{j(\text{init})} = 25\text{ }^{\circ}\text{C}$ ; $t_p = 20\text{ ms}$ ; <a href="#">Fig. 4</a> ; <a href="#">Fig. 5</a> | -   | 95  | A                      |
|              |                                      | full sine wave; $T_{j(\text{init})} = 25\text{ }^{\circ}\text{C}$ ; $t_p = 16.7\text{ ms}$   | -   | 105 | A                      |
| $I^2t$       | $I^2t$ for fusing                    | $t_p = 10\text{ ms}$ ; sine-wave pulse   | -   | 45  | $\text{A}^2\text{s}$   |
| $di_T/dt$    | rate of rise of on-state current     | $I_G = 50\text{ mA}$   | -   | 50  | $\text{A}/\mu\text{s}$ |
| $I_{GM}$     | peak gate current                    |  | -   | 2   | A                      |
| $P_{GM}$     | peak gate power                      |  | -   | 5   | W                      |
| $P_{G(AV)}$  | average gate power                   | over any 20 ms period  | -   | 0.5 | W                      |
| $T_{stg}$    | storage temperature                  |  | -40 | 150 | $^{\circ}\text{C}$     |
| $T_j$        | junction temperature                 |  | -   | 125 | $^{\circ}\text{C}$     |



**Fig. 1. RMS on-state current as a function of mounting base temperature; maximum values**



$f = 50\text{ Hz}$ ;  $T_{mb} = 99\text{ }^{\circ}\text{C}$

**Fig. 2. RMS on-state current as a function of surge duration; maximum values**

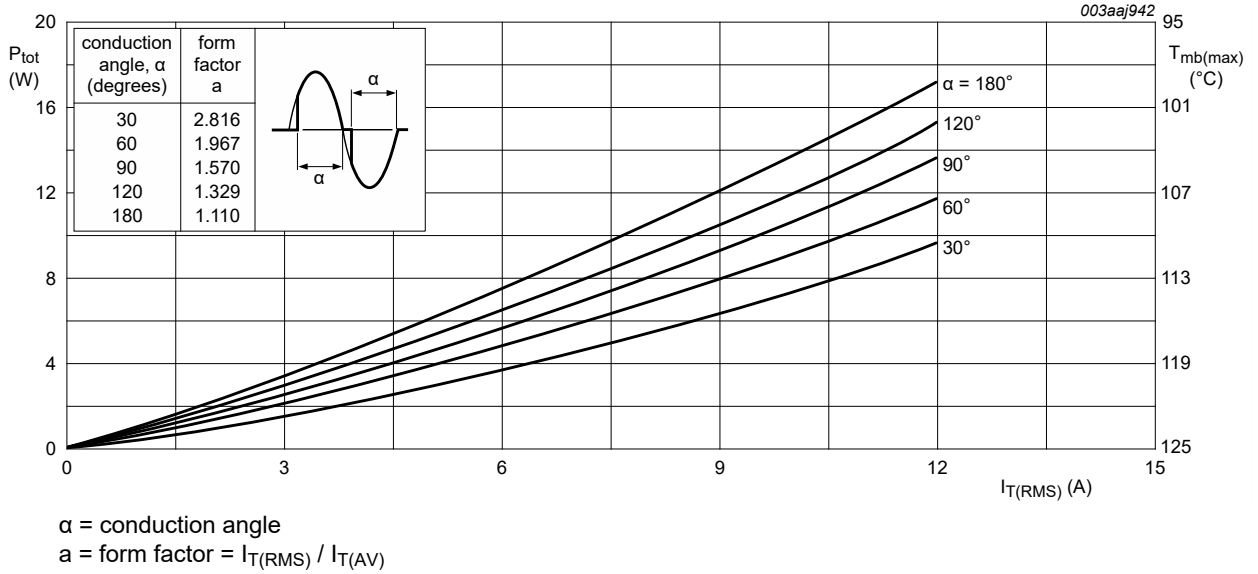


Fig. 3. Total power dissipation as a function of RMS on-state current; maximum values

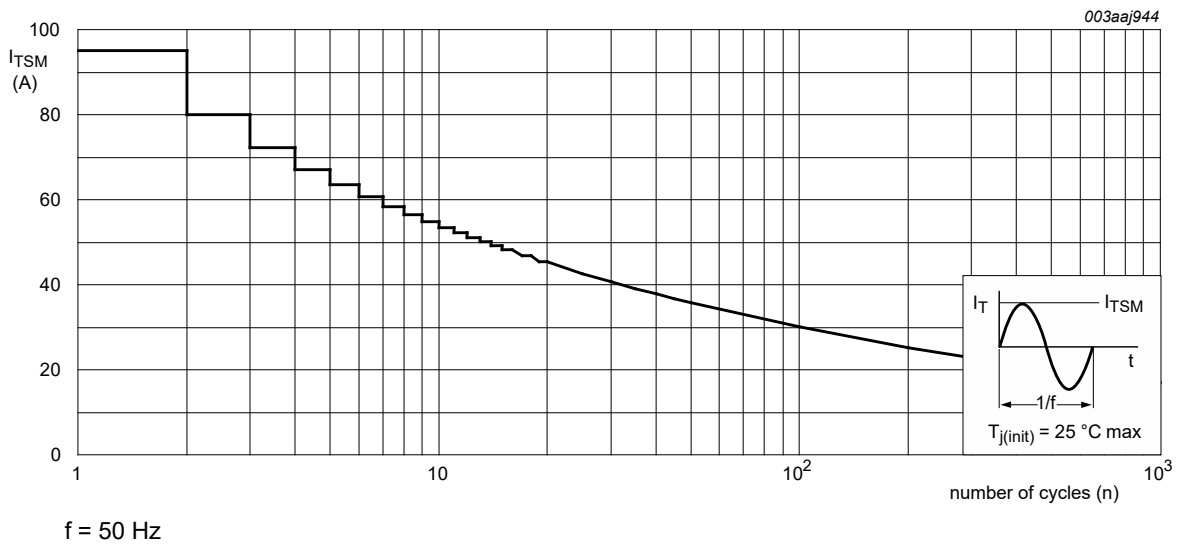
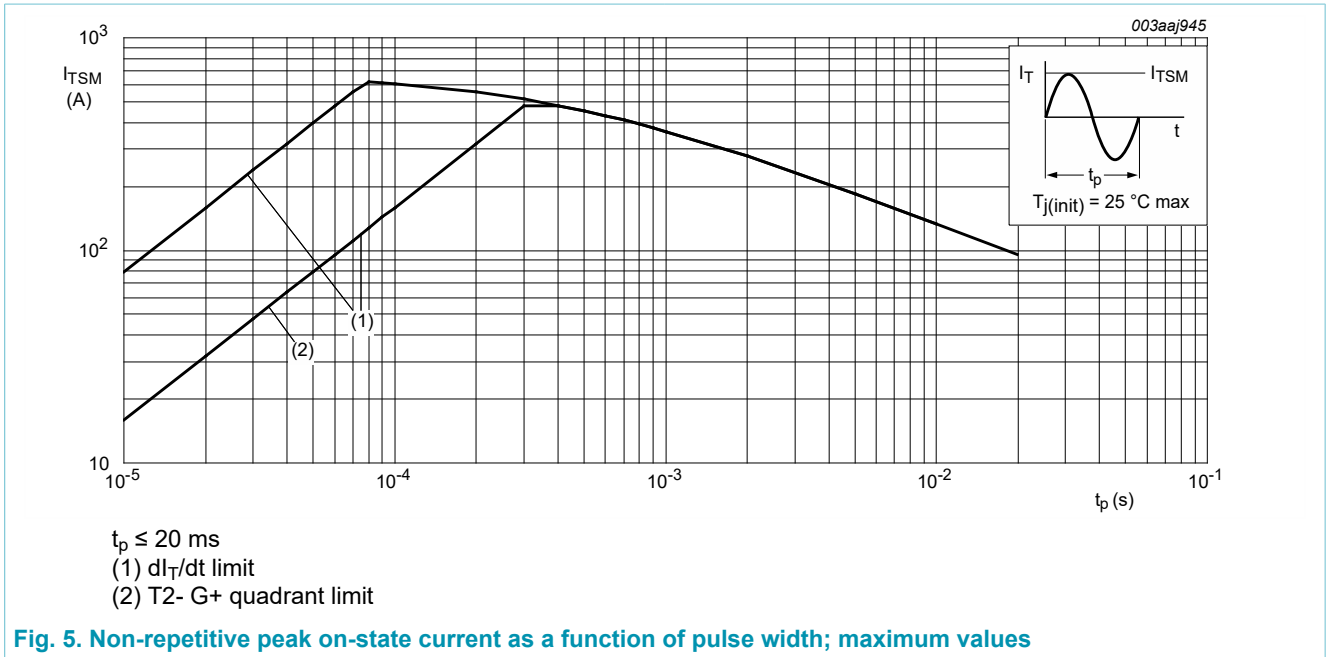


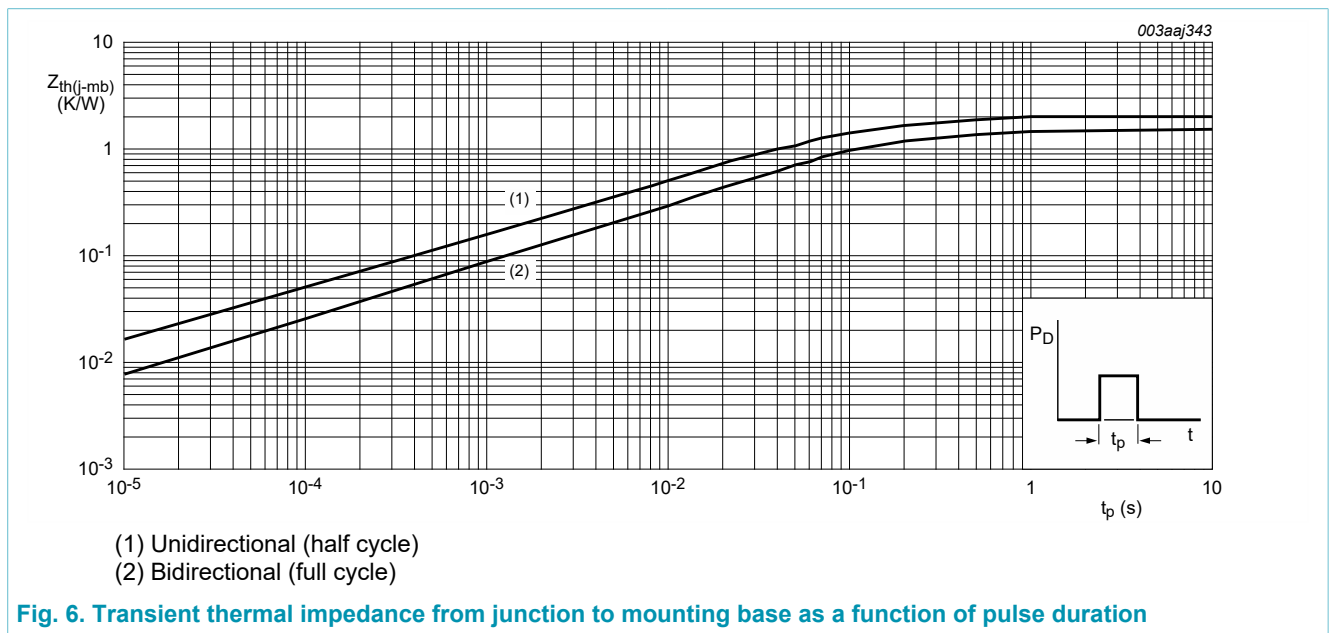
Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values



## 8. Thermal characteristics

Table 5. Thermal characteristics

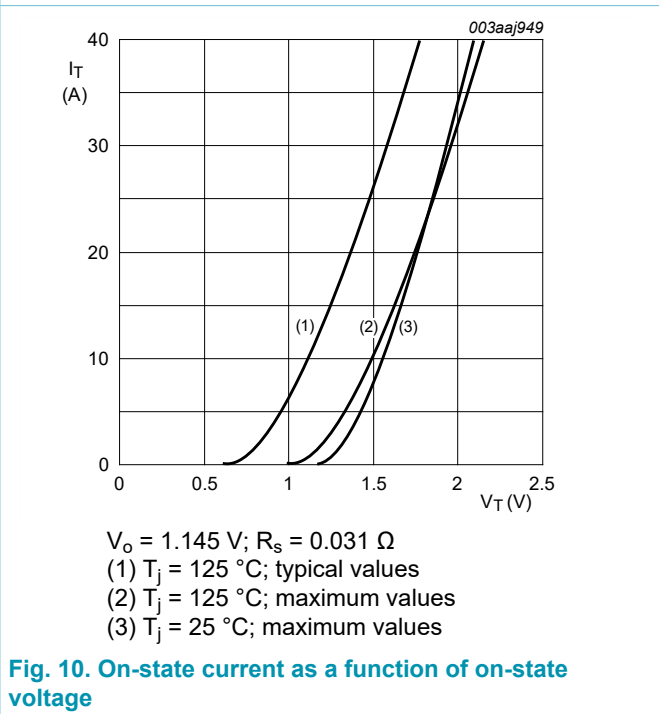
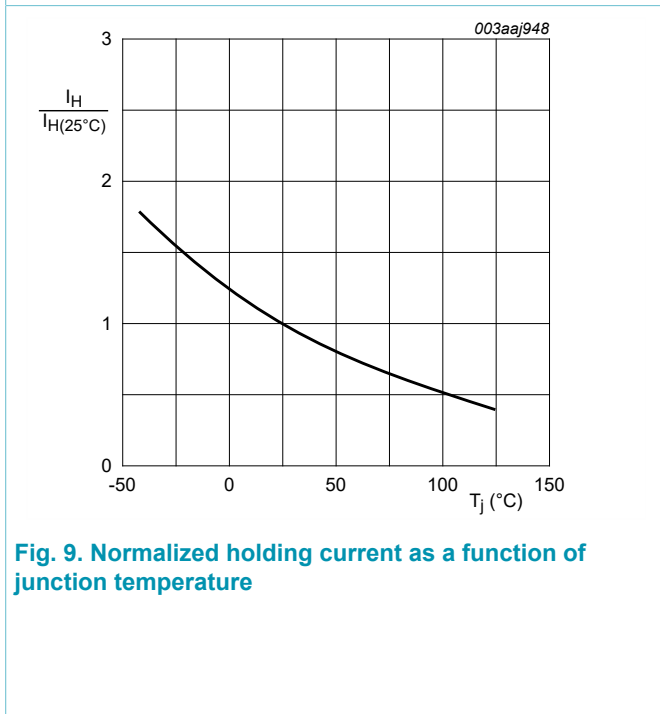
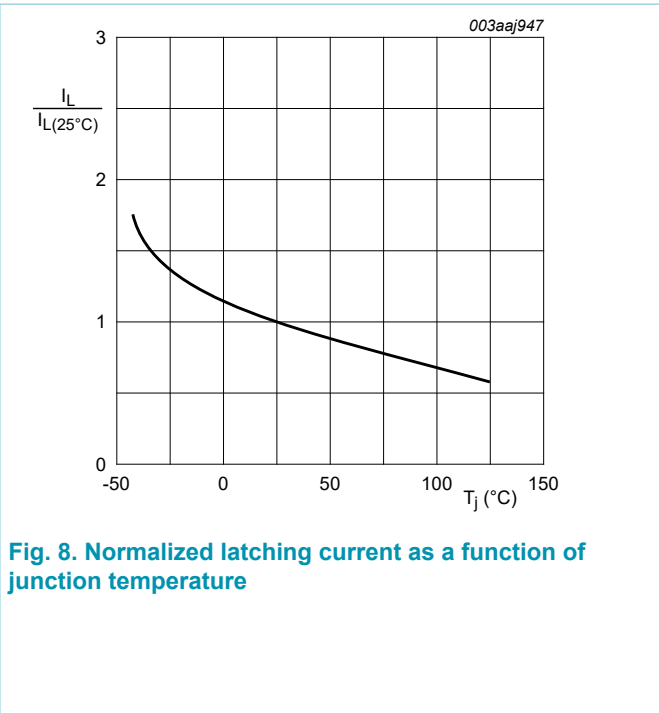
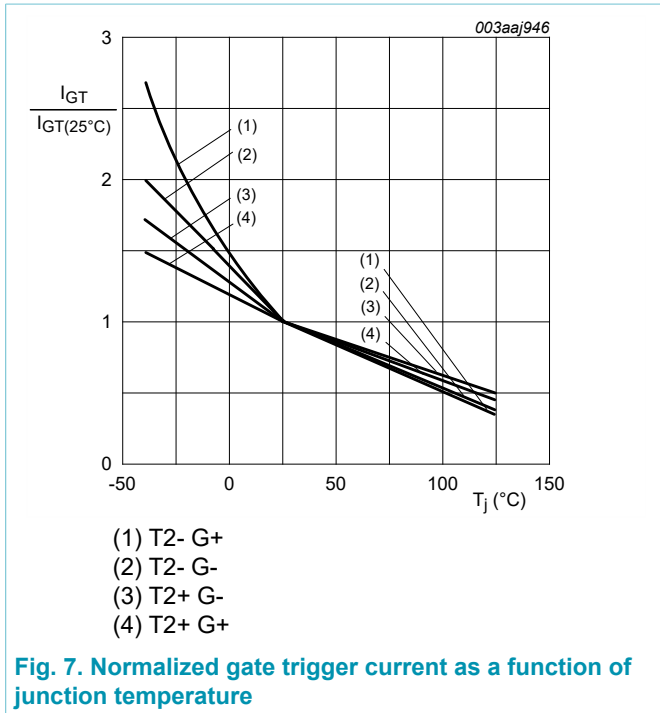
| Symbol         | Parameter  | Conditions                   | Min | Typ | Max | Unit |
|----------------|--|------------------------------|-----|-----|-----|------|
| $R_{th(j-mb)}$ | thermal resistance from junction to mounting base    | full cycle; Fig. 6           | -   | -   | 1.5 | K/W  |
|                |  | half cycle; Fig. 6           | -   | -   | 2   | K/W  |
| $R_{th(j-a)}$  | thermal resistance from junction to ambient free air | minimum footprint: FR4 board | -   | 55  | -   | K/W  |



## 9. Characteristics

Table 6. Characteristics

| Symbol                         | Parameter                         | Conditions  | Min  | Typ | Max  | Unit             |
|--------------------------------|-----------------------------------|---|------|-----|------|------------------|
| <b>Static characteristics</b>  |                                   |   |      |     |      |                  |
| $I_{GT}$                       | gate trigger current              | $V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; T2+ G+;<br>$T_j = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 7</a>                       | -    | 2.5 | 10   | mA               |
|                                |                                   | $V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; T2+ G-;<br>$T_j = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 7</a>                       | -    | 4   | 10   | mA               |
|                                |                                   | $V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; T2- G-;<br>$T_j = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 7</a>                       | -    | 5   | 10   | mA               |
|                                |                                   | $V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; T2- G+;<br>$T_j = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 7</a>                       | -    | 11  | 25   | mA               |
| $I_L$                          | latching current                  | $V_D = 12\text{ V}$ ; $I_G = 0.1\text{ A}$ ; T2+ G+;<br>$T_j = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 8</a>                       | -    | 3.2 | 30   | mA               |
|                                |                                   | $V_D = 12\text{ V}$ ; $I_G = 0.1\text{ A}$ ; T2+ G-;<br>$T_j = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 8</a>                       | -    | 16  | 40   | mA               |
|                                |                                   | $V_D = 12\text{ V}$ ; $I_G = 0.1\text{ A}$ ; T2- G-;<br>$T_j = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 8</a>                       | -    | 4   | 30   | mA               |
|                                |                                   | $V_D = 12\text{ V}$ ; $I_G = 0.1\text{ A}$ ; T2- G+;<br>$T_j = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 8</a>                       | -    | 5.5 | 40   | mA               |
| $I_H$                          | holding current                   | $V_D = 12\text{ V}$ ; $T_j = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 9</a>   | -    | 4   | 30   | mA               |
| $V_T$                          | on-state voltage                  | $I_T = 15\text{ A}$ ; $T_j = 25\text{ }^\circ\text{C}$ ; <a href="#">Fig. 10</a>  | -    | 1.4 | 1.65 | V                |
| $V_{GT}$                       | gate trigger voltage              | $V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; $T_j = 25\text{ }^\circ\text{C}$ ;<br><a href="#">Fig. 11</a>                              | -    | 0.7 | 1    | V                |
|                                |                                   | $V_D = 400\text{ V}$ ; $I_T = 0.1\text{ A}$ ; $T_j = 125\text{ }^\circ\text{C}$ ;<br><a href="#">Fig. 11</a>                            | 0.25 | 0.4 | -    | V                |
| $I_D$                          | off-state current                 | $V_D = 600\text{ V}$ ; $T_j = 125\text{ }^\circ\text{C}$  | -    | 0.1 | 0.5  | mA               |
| <b>Dynamic characteristics</b> |                                   |   |      |     |      |                  |
| $dV_D/dt$                      | rate of rise of off-state voltage | $V_{DM} = 402\text{ V}$ ; $T_j = 125\text{ }^\circ\text{C}$ ; ( $V_{DM} = 67\%$ of $V_{DRM}$ ); exponential waveform; gate open circuit | -    | 50  | -    | V/ $\mu\text{s}$ |



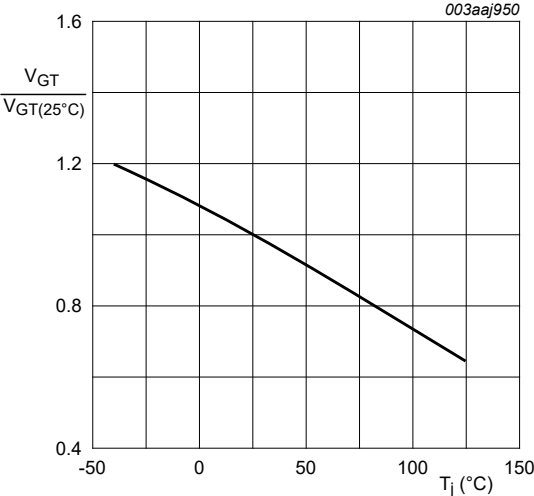


Fig. 11. Normalized gate trigger voltage as a function of junction temperature



10. Package outline

Plastic single-ended surface-mounted package (D2PAK); 3 leads (one lead cropped) TO263

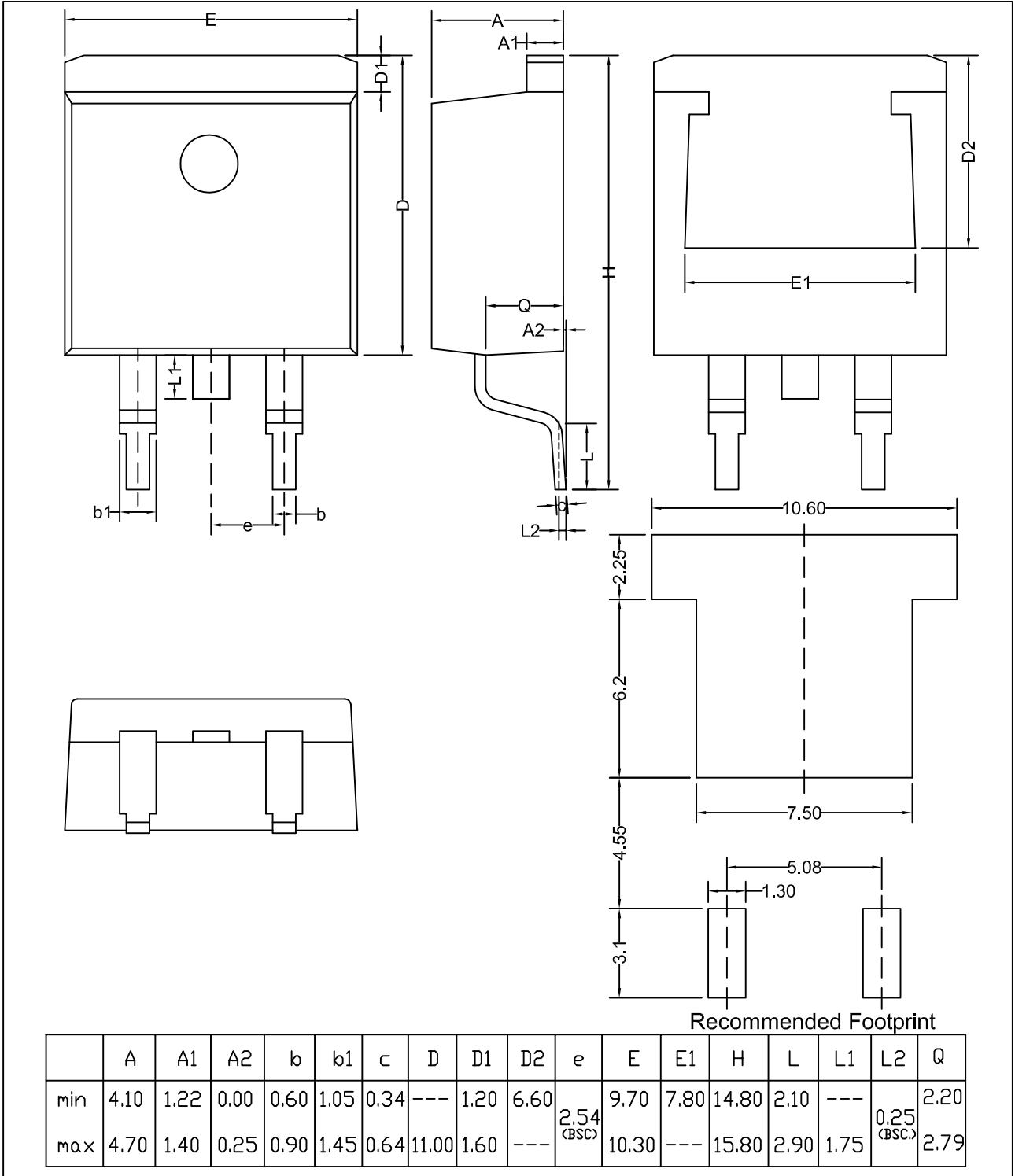


Fig. 12. Package outline D2PAK (SOT404)

## 11. Legal information

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| Document status [1][2]         | Product status [3] | Definition  |
|--------------------------------|--------------------|---|
| Objective [short] data sheet   | Development        | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification      | This document contains data from the preliminary specification.                       |
| Product [short] data sheet     | Production         | This document contains the product specification.                                     |

- [1] Please consult the most recently issued document before initiating or completing a design.
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